

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



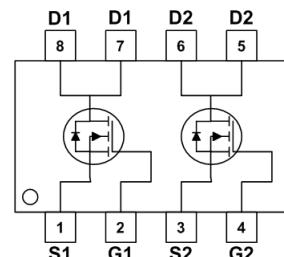
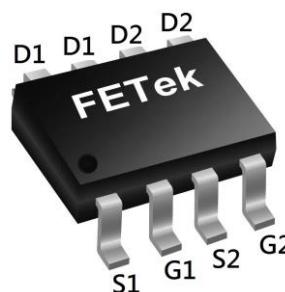
| BVDSS | RDS(ON) | ID |
|-------|---------|-----|
| 30V | 12mΩ | 10A |

Description

The FKS3214 is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The FKS3214 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Dual SOP8 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|--------------------------------------|--|------------|-------|
| V _{DS} | Drain-Source Voltage | 30 | V |
| V _{GS} | Gate-Source Voltage | ±20 | V |
| I _D @T _A =25°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 10 | A |
| I _D @T _A =70°C | Continuous Drain Current, V _{GS} @ 10V ¹ | 8 | A |
| I _{DM} | Pulsed Drain Current ² | 36 | A |
| EAS | Single Pulse Avalanche Energy ³ | 24.2 | mJ |
| I _{AS} | Avalanche Current | 22 | A |
| P _D @T _A =25°C | Total Power Dissipation ⁴ | 1.5 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-Ambient ¹ | --- | 85 | °C/W |
| R _{θJL} | Thermal Resistance Junction-Case ¹ | --- | 25 | °C/W |

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

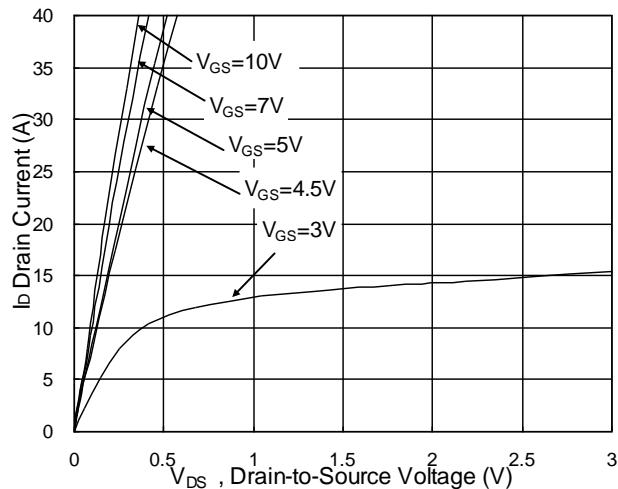
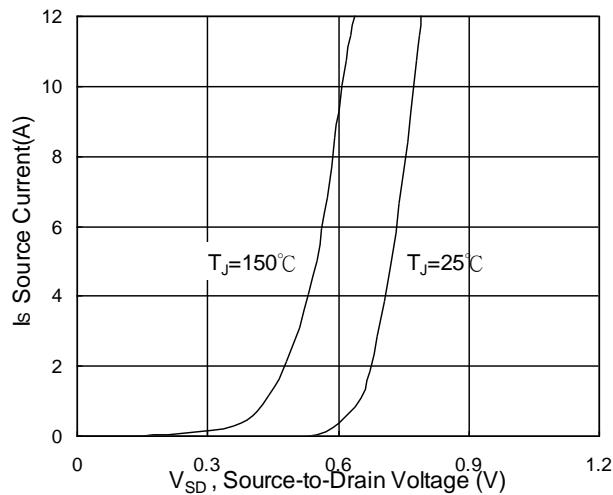
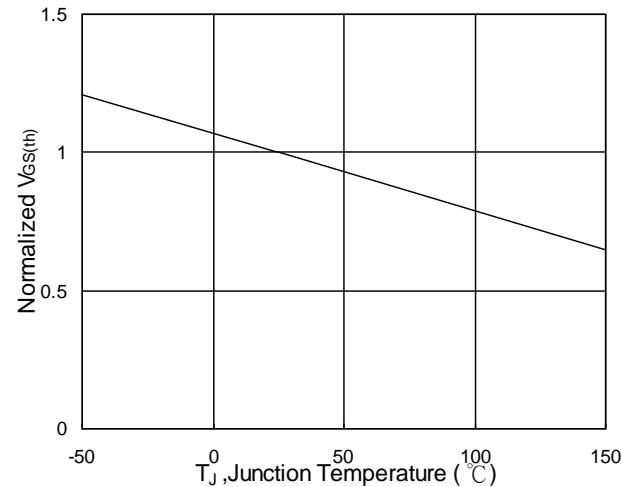
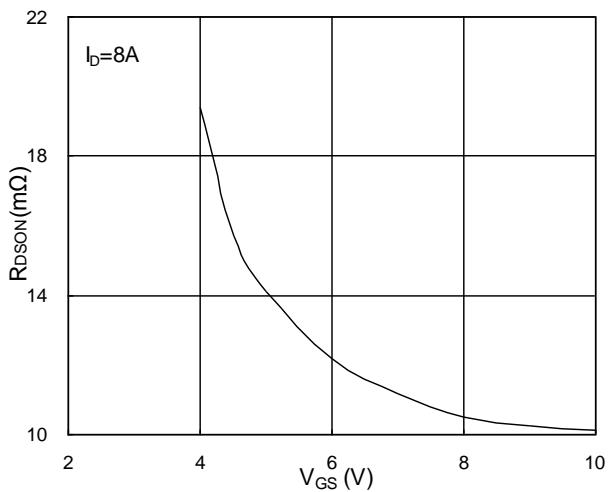
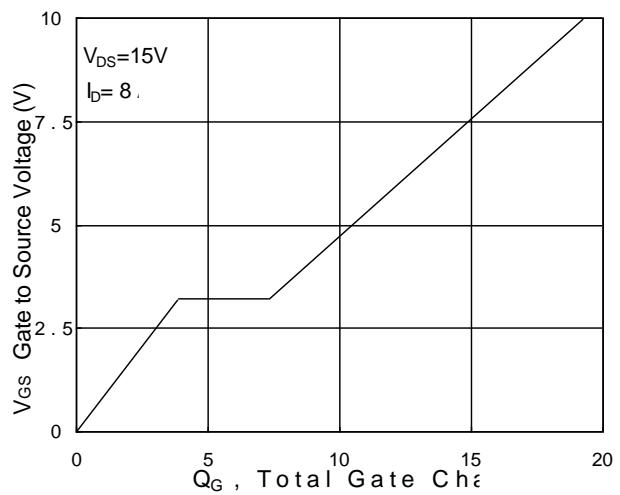
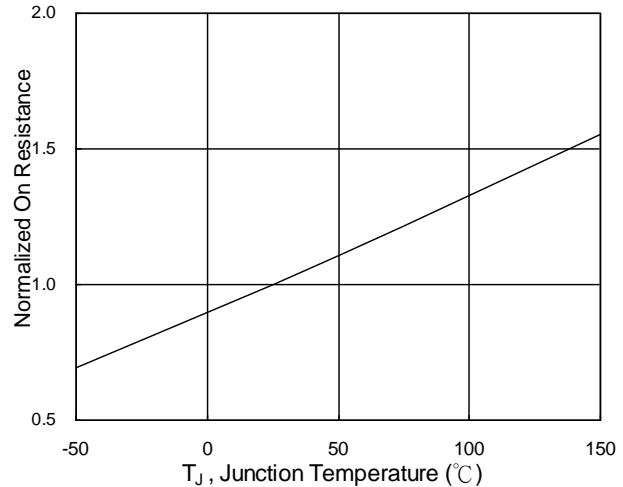
| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|--|--|---|------|-------|-----------|----------------------------|
| BV_{DSS} | Drain-Source Breakdown Voltage | $V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$ | 30 | --- | --- | V |
| $\Delta \text{BV}_{\text{DSS}}/\Delta T_J$ | BV_{DSS} Temperature Coefficient | Reference to 25°C , $I_D=1\text{mA}$ | --- | 0.023 | --- | $\text{V}/^\circ\text{C}$ |
| $R_{\text{DS}(\text{ON})}$ | Static Drain-Source On-Resistance ² | $V_{\text{GS}}=10\text{V}$, $I_D=8\text{A}$ | --- | --- | 12 | $\text{m}\Omega$ |
| | | $V_{\text{GS}}=4.5\text{V}$, $I_D=6\text{A}$ | --- | --- | 18 | |
| $V_{\text{GS}(\text{th})}$ | Gate Threshold Voltage | $V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$ | 1.2 | --- | 2.5 | V |
| $\Delta V_{\text{GS}(\text{th})}$ | $V_{\text{GS}(\text{th})}$ Temperature Coefficient | | --- | -5.08 | --- | $\text{mV}/^\circ\text{C}$ |
| I_{DSS} | Drain-Source Leakage Current | $V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | uA |
| | | $V_{\text{DS}}=24\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$ | --- | --- | 5 | |
| I_{GSS} | Gate-Source Leakage Current | $V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$ | --- | --- | ± 100 | nA |
| g_{fs} | Forward Transconductance | $V_{\text{DS}}=5\text{V}$, $I_D=8\text{A}$ | --- | 24 | --- | S |
| R_g | Gate Resistance | $V_{\text{DS}}=0\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 1.8 | --- | Ω |
| Q_g | Total Gate Charge (4.5V) | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=8\text{A}$ | --- | 9.63 | --- | nC |
| Q_{gs} | Gate-Source Charge | | --- | 3.88 | --- | |
| Q_{gd} | Gate-Drain Charge | | --- | 3.44 | --- | |
| $T_{\text{d}(\text{on})}$ | Turn-On Delay Time | $V_{\text{DD}}=15\text{V}$, $V_{\text{GS}}=10\text{V}$, $R_G=1.5\Omega$ | --- | 4.2 | --- | ns |
| T_r | Rise Time | | --- | 8.2 | --- | |
| $T_{\text{d}(\text{off})}$ | Turn-Off Delay Time | | --- | 31 | --- | |
| T_f | Fall Time | | --- | 4 | --- | |
| C_{iss} | Input Capacitance | $V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$ | --- | 940 | --- | pF |
| C_{oss} | Output Capacitance | | --- | 131 | --- | |
| C_{rss} | Reverse Transfer Capacitance | | --- | 109 | --- | |

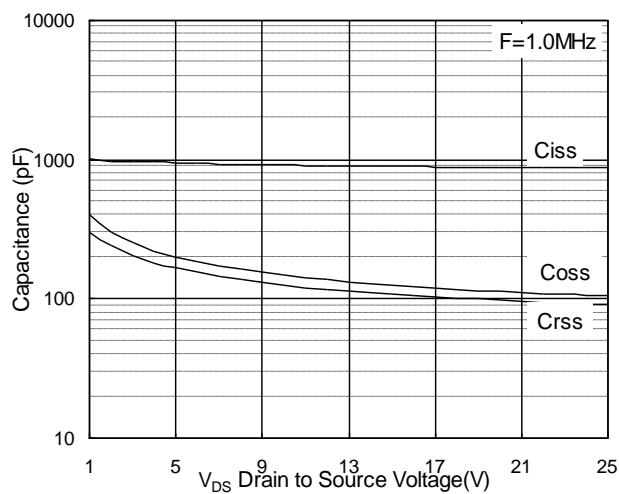
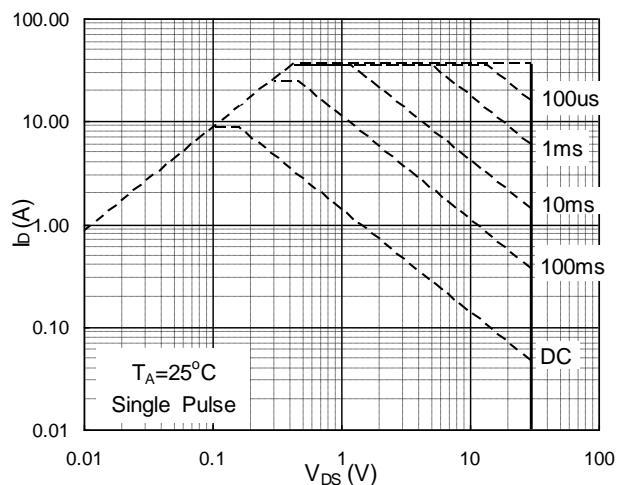
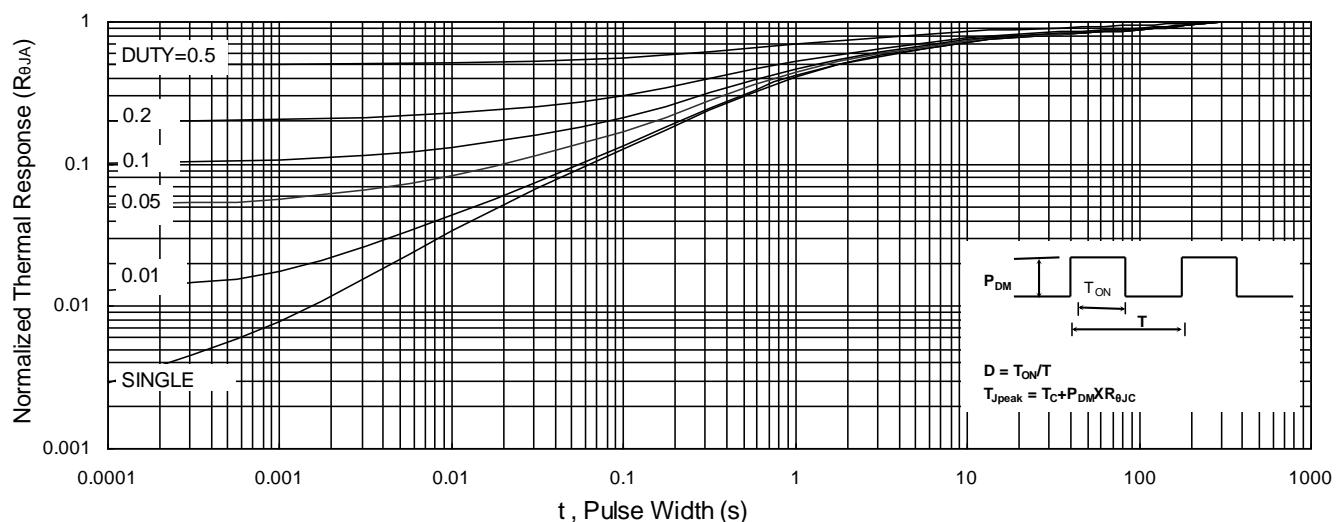
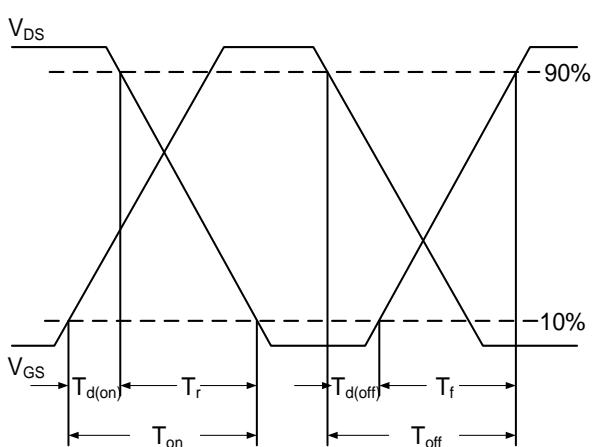
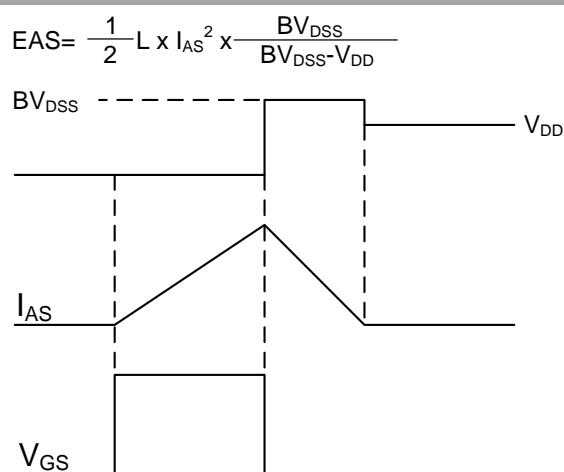
Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|-------------|
| I_s | Continuous Source Current ^{1,5} | $V_G=V_D=0\text{V}$, Force Current | --- | --- | 9 | A |
| V_{SD} | Diode Forward Voltage ² | $V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$ | --- | --- | 1 | V |
| t_{rr} | Reverse Recovery Time | $I_F=8\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, | --- | 8 | --- | nS |
| | | $T_J=25^\circ\text{C}$ | --- | 2.9 | --- | nC |

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=25\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.1\text{mH}$, $I_{\text{AS}}=22\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

Fig.1 Typical Output Characteristics

Fig.3 Source Drain Forward Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs. T_J
Dual N-Ch 30V Fast Switching MOSFETs

Fig.2 On-Resistance vs. G-S Voltage

Fig.4 Gate-Charge Characteristics

Fig.6 Normalized R_{DSON} vs. T_J


Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform